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Kind regards,

Team Nexperia

# 74LVC2G66-Q100

## Bilateral switch

Rev. 2 — 14 December 2016

Product data sheet

## 1. General description

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The 74LVC2G66-Q100 is a low-power, low-voltage, high-speed Si-gate CMOS device.

The 74LVC2G66-Q100 provides two single pole, single-throw analog switch functions. Each switch has two input/output terminals (nY and nZ) and an active HIGH enable input (nE). When nE is LOW, the analog switch is turned off.

Schmitt trigger action at the enable inputs makes the circuit tolerant of slower input rise and fall times across the entire  $V_{CC}$  range from 1.65 V to 5.5 V.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

## 2. Features and benefits

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- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
  - ◆ Specified from  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$  and from  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$
- Wide supply voltage range from 1.65 V to 5.5 V
- Very low ON resistance:
  - ◆  $7.5\ \Omega$  (typical) at  $V_{CC} = 2.7\ \text{V}$
  - ◆  $6.5\ \Omega$  (typical) at  $V_{CC} = 3.3\ \text{V}$
  - ◆  $6\ \Omega$  (typical) at  $V_{CC} = 5\ \text{V}$
- Switch current capability of 32 mA
- High noise immunity
- CMOS low power consumption
- TTL interface compatibility at 3.3 V
- Latch-up performance meets requirements of JESD78 Class I
- ESD protection:
  - ◆ MIL-STD-883, method 3015 exceeds 2000 V
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V ( $C = 200\ \text{pF}$ ,  $R = 0\ \Omega$ )
- Enable input accepts voltages up to 5.5 V



### 3. Ordering information

### Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74LVC2G66DP-Q100	−40 °C to +125 °C	TSSOP8	plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm	SOT505-2
74LVC2G66DC-Q100	−40 °C to +125 °C	VSSOP8	plastic very thin shrink small outline package; 8 leads; body width 2.3 mm	SOT765-1

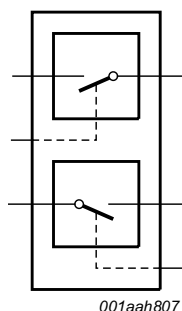
## 4. Marking

### Table 2. Marking codes

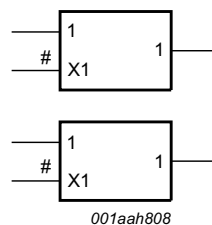
Type number	Marking code <sup>[1]</sup>
74LVC2G66DP-Q100	V66
74LVC2G66DC-Q100	V66

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

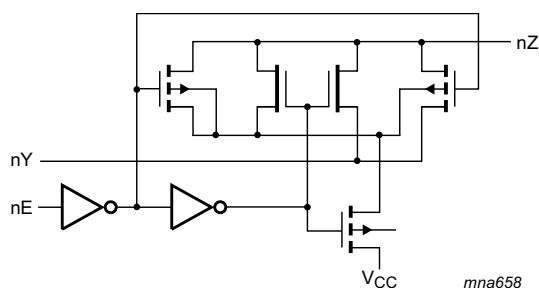
## 5. Functional diagram



**Fig 1. Logic symbol**



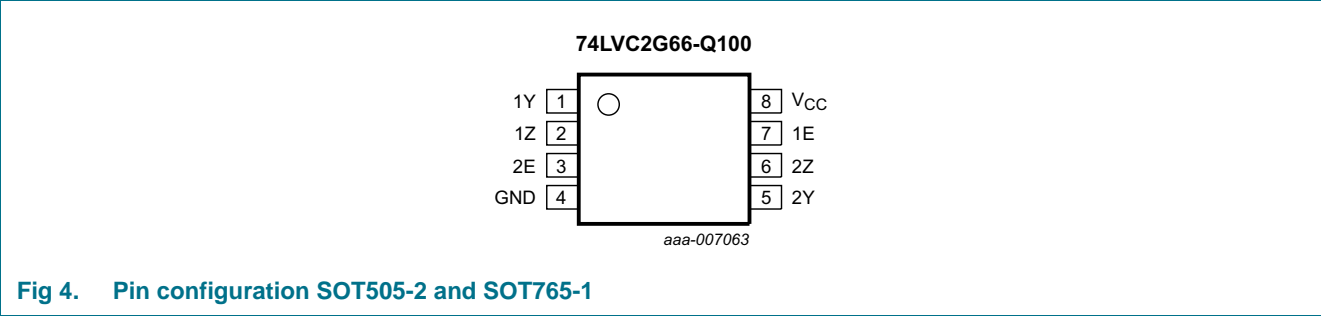
**Fig 2. IEC logic symbol**



**Fig 3. Logic diagram (one switch)**

## 6. Pinning information

### 6.1 Pinning



### 6.2 Pin description

Table 3. Pin description

Symbol	Pin	Symbol
1Y	1	independent input or output
1Z	2	independent input or output
2E	3	enable input (active HIGH)
GND	4	ground (0 V)
2Y	5	independent input or output
2Z	6	independent input or output
1E	7	enable input (active HIGH)
V <sub>CC</sub>	8	supply voltage

## 7. Functional description

Table 4. Function table<sup>[1]</sup>

Input nE	Switch
L	OFF-state
H	ON-state

[1] H = HIGH voltage level; L = LOW voltage level.

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+6.5	V
$V_I$	input voltage	[1]	-0.5	+6.5	V
$I_{IK}$	input clamping current	$V_I < -0.5\text{ V}$ or $V_I > V_{CC} + 0.5\text{ V}$	-50	-	mA
$I_{SK}$	switch clamping current	$V_I < -0.5\text{ V}$ or $V_I > V_{CC} + 0.5\text{ V}$	-	$\pm 50$	mA
$V_{SW}$	switch voltage	enable and disable mode [2]	-0.5	$V_{CC} + 0.5$	V
$I_{SW}$	switch current	$V_{SW} > -0.5\text{ V}$ or $V_{SW} < V_{CC} + 0.5\text{ V}$	-	$\pm 50$	mA
$I_{CC}$	supply current		-	100	mA
$I_{GND}$	ground current		-100	-	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation	$T_{amb} = -40\text{ °C}$ to $+125\text{ °C}$ [3]	-	250	mW

[1] The minimum input voltage rating may be exceeded if the input current rating is observed.

[2] The minimum and maximum switch voltage ratings may be exceeded if the switch clamping current rating is observed.

[3] For TSSOP8 package: above 55 °C the value of  $P_{tot}$  derates linearly with 2.5 mW/K.  
For VSSOP8 package: above 110 °C the value of  $P_{tot}$  derates linearly with 8 mW/K.

## 9. Recommended operating conditions

**Table 6. Operating conditions**

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		1.65	5.5	V
$V_I$	input voltage		0	5.5	V
$V_{SW}$	switch voltage	[1]	0	$V_{CC}$	V
$T_{amb}$	ambient temperature		-40	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 1.65\text{ V}$ to $2.7\text{ V}$ [2]	-	20	ns/V
		$V_{CC} = 2.7\text{ V}$ to $5.5\text{ V}$ [2]	-	10	ns/V

[1] To avoid sinking GND current from terminal nZ when switch current flows in terminal nY, the voltage drop across the bidirectional switch must not exceed 0.4 V. If the switch current flows into terminal nZ, no GND current flows from terminal nY. In this case, there is no limit for the voltage drop across the switch.

[2] Applies to control signal levels.

## 10. Static characteristics

**Table 7. Static characteristics**

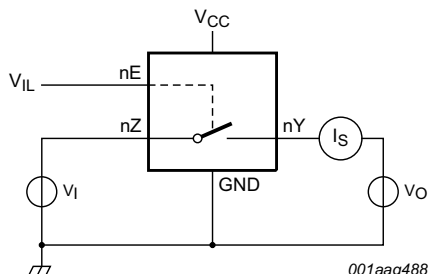
At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>	-	-	0.65 × V <sub>CC</sub>	-	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.7	-	-	1.7	-	V
		V <sub>CC</sub> = 2.7 V to 3.6 V	2.0	-	-	2.0	-	V
		V <sub>CC</sub> = 4.5 V to 5.5 V	0.7 × V <sub>CC</sub>	-	-	0.7 × V <sub>CC</sub>	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V	-	-	0.35 × V <sub>CC</sub>	-	0.35 × V <sub>CC</sub>	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	-	0.7	-	0.7	V
		V <sub>CC</sub> = 2.7 V to 3.6 V	-	-	0.8	-	0.8	V
		V <sub>CC</sub> = 4.5 V to 5.5 V	-	-	0.3 × V <sub>CC</sub>	-	0.3 × V <sub>CC</sub>	V
I <sub>I</sub>	input leakage current	pin nE; V <sub>I</sub> = 5.5 V or GND; V <sub>CC</sub> = 0 V to 5.5 V <sup>[2]</sup>	-	±0.1	±1	-	±1	μA
I <sub>S(OFF)</sub>	OFF-state leakage current	V <sub>CC</sub> = 5.5 V; see <a href="#">Figure 5</a> <sup>[2]</sup>	-	±0.1	±0.2	-	±0.5	μA
I <sub>S(ON)</sub>	ON-state leakage current	V <sub>CC</sub> = 5.5 V; see <a href="#">Figure 6</a> <sup>[2]</sup>	-	±0.1	±1	-	±2	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = 5.5 V or GND; V <sub>SW</sub> = GND or V <sub>CC</sub> ; V <sub>CC</sub> = 1.65 V to 5.5 V <sup>[2]</sup>	-	0.1	4	-	4	μA
ΔI <sub>CC</sub>	additional supply current	pin nE; V <sub>I</sub> = V <sub>CC</sub> – 0.6 V; V <sub>SW</sub> = GND or V <sub>CC</sub> ; V <sub>CC</sub> = 5.5 V <sup>[2]</sup>	-	5	500	-	500	μA
C <sub>I</sub>	input capacitance		-	2.0	-	-	-	pF
C <sub>S(OFF)</sub>	OFF-state capacitance		-	5.0	-	-	-	pF
C <sub>S(ON)</sub>	ON-state capacitance		-	9.5	-	-	-	pF

[1] All typical values are measured at T<sub>amb</sub> = 25 °C.

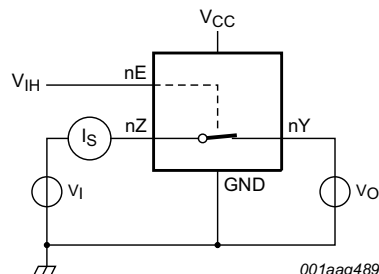
[2] These typical values are measured at V<sub>CC</sub> = 3.3 V.

## 10.1 Test circuits



$V_I = V_{CC}$  or GND and  $V_O =$  GND or  $V_{CC}$ .

**Fig 5. Test circuit for measuring OFF-state leakage current**



$V_I = V_{CC}$  or GND and  $V_O =$  open circuit.

**Fig 6. Test circuit for measuring ON-state leakage current**

## 10.2 ON resistance

**Table 8. ON resistance**

At recommended operating conditions; voltages are referenced to GND (ground 0 V); for graphs see [Figure 8](#) to [Figure 13](#).

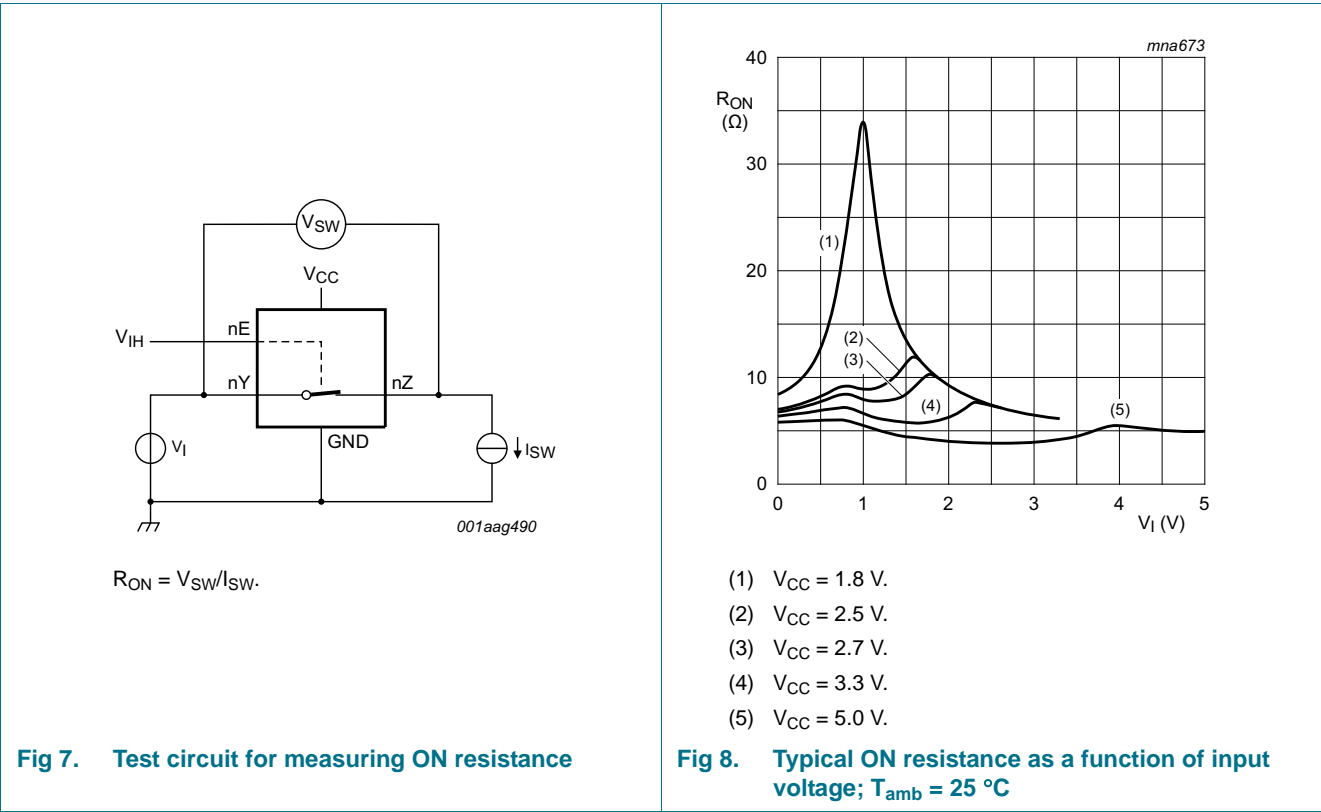
Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
$R_{ON(peak)}$	ON resistance (peak)	$V_I =$ GND to $V_{CC}$ ; see <a href="#">Figure 7</a>						
		$I_{SW} = 4$ mA; $V_{CC} = 1.65$ V to 1.95 V	-	34.0	130	-	195	$\Omega$
		$I_{SW} = 8$ mA; $V_{CC} = 2.3$ V to 2.7 V	-	12.0	30	-	45	$\Omega$
		$I_{SW} = 12$ mA; $V_{CC} = 2.7$ V	-	10.4	25	-	38	$\Omega$
		$I_{SW} = 24$ mA; $V_{CC} = 3.0$ V to 3.6 V	-	7.8	20	-	30	$\Omega$
		$I_{SW} = 32$ mA; $V_{CC} = 4.5$ V to 5.5 V	-	6.2	15	-	23	$\Omega$
$R_{ON(rail)}$	ON resistance (rail)	$V_I =$ GND; see <a href="#">Figure 7</a>						
		$I_{SW} = 4$ mA; $V_{CC} = 1.65$ V to 1.95 V	-	8.2	18	-	27	$\Omega$
		$I_{SW} = 8$ mA; $V_{CC} = 2.3$ V to 2.7 V	-	7.1	16	-	24	$\Omega$
		$I_{SW} = 12$ mA; $V_{CC} = 2.7$ V	-	6.9	14	-	21	$\Omega$
		$I_{SW} = 24$ mA; $V_{CC} = 3.0$ V to 3.6 V	-	6.5	12	-	18	$\Omega$
		$I_{SW} = 32$ mA; $V_{CC} = 4.5$ V to 5.5 V	-	5.8	10	-	15	$\Omega$
		$V_I = V_{CC}$ ; see <a href="#">Figure 7</a>						
		$I_{SW} = 4$ mA; $V_{CC} = 1.65$ V to 1.95 V	-	10.4	30	-	45	$\Omega$
		$I_{SW} = 8$ mA; $V_{CC} = 2.3$ V to 2.7 V	-	7.6	20	-	30	$\Omega$
		$I_{SW} = 12$ mA; $V_{CC} = 2.7$ V	-	7.0	18	-	27	$\Omega$
		$I_{SW} = 24$ mA; $V_{CC} = 3.0$ V to 3.6 V	-	6.1	15	-	23	$\Omega$
		$I_{SW} = 32$ mA; $V_{CC} = 4.5$ V to 5.5 V	-	4.9	10	-	15	$\Omega$

**Table 8. ON resistance ...continued**  
 At recommended operating conditions; voltages are referenced to GND (ground 0 V); for graphs see [Figure 8](#) to [Figure 13](#).

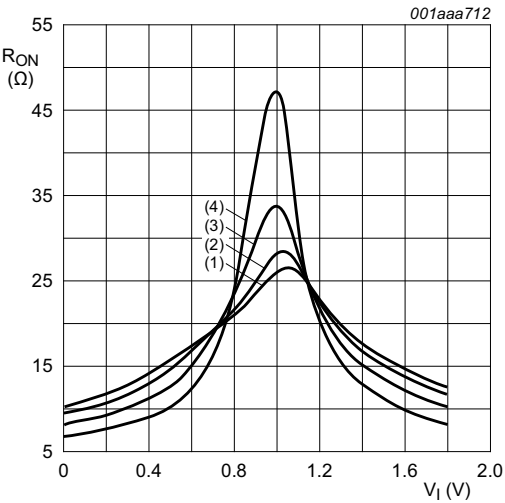
Symbol	Parameter	Conditions	−40 °C to +85 °C			−40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
R <sub>ON(flat)</sub>	ON resistance (flatness)	V <sub>I</sub> = GND to V <sub>CC</sub> <sup>[2]</sup>						
		I <sub>SW</sub> = 4 mA; V <sub>CC</sub> = 1.65 V to 1.95 V	-	26.0	-	-	-	Ω
		I <sub>SW</sub> = 8 mA; V <sub>CC</sub> = 2.3 V to 2.7 V	-	5.0	-	-	-	Ω
		I <sub>SW</sub> = 12 mA; V <sub>CC</sub> = 2.7 V	-	3.5	-	-	-	Ω
		I <sub>SW</sub> = 24 mA; V <sub>CC</sub> = 3.0 V to 3.6 V	-	2.0	-	-	-	Ω
		I <sub>SW</sub> = 32 mA; V <sub>CC</sub> = 4.5 V to 5.5 V	-	1.5	-	-	-	Ω

- [1] Typical values are measured at T<sub>amb</sub> = 25 °C and nominal V<sub>CC</sub>.
- [2] Flatness is defined as the difference between the maximum and minimum value of ON resistance measured at identical V<sub>CC</sub> and temperature.

10.3 ON resistance test circuit and graphs

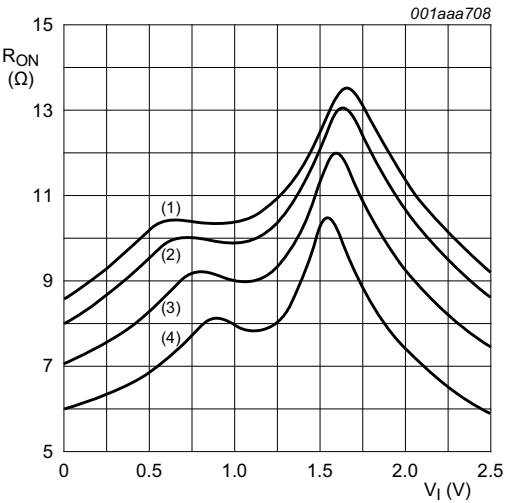






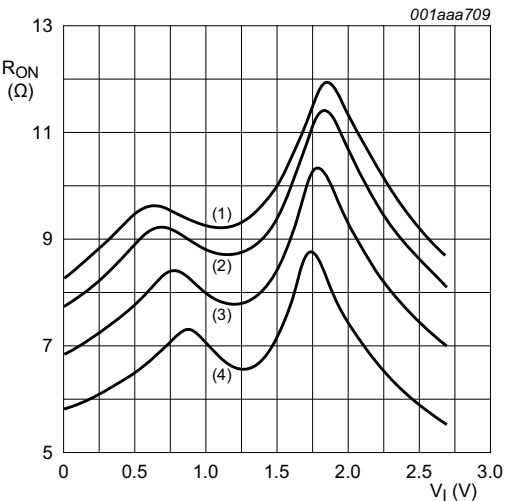
- (1)  $T_{amb} = 125$  °C.
- (2)  $T_{amb} = 85$  °C.
- (3)  $T_{amb} = 25$  °C.
- (4)  $T_{amb} = -40$  °C.

Fig 9. ON resistance as a function of input voltage;  $V_{CC} = 1.8$  V



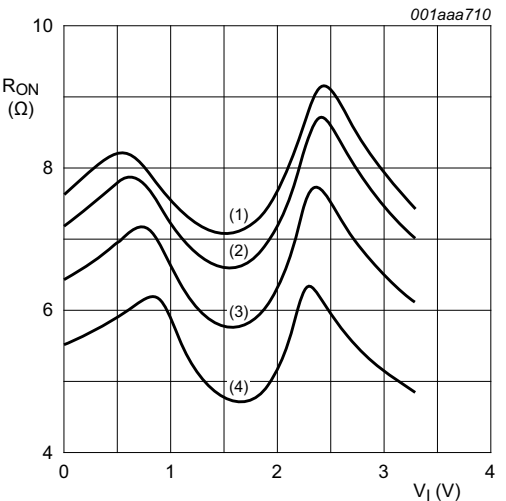
- (1)  $T_{amb} = 125$  °C.
- (2)  $T_{amb} = 85$  °C.
- (3)  $T_{amb} = 25$  °C.
- (4)  $T_{amb} = -40$  °C.

Fig 10. ON resistance as a function of input voltage;  $V_{CC} = 2.5$  V



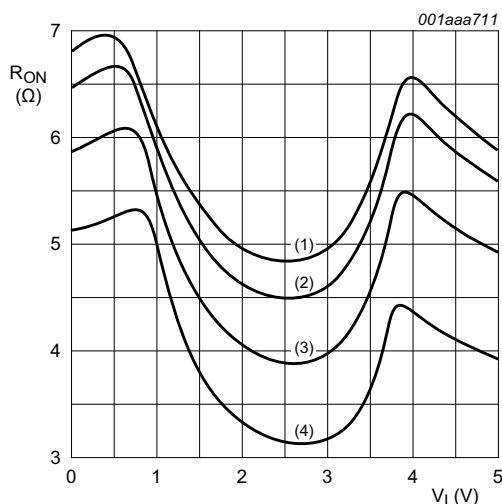
- (1)  $T_{amb} = 125$  °C.
- (2)  $T_{amb} = 85$  °C.
- (3)  $T_{amb} = 25$  °C.
- (4)  $T_{amb} = -40$  °C.

Fig 11. ON resistance as a function of input voltage;  $V_{CC} = 2.7$  V



- (1)  $T_{amb} = 125$  °C.
- (2)  $T_{amb} = 85$  °C.
- (3)  $T_{amb} = 25$  °C.
- (4)  $T_{amb} = -40$  °C.

Fig 12. ON resistance as a function of input voltage;  $V_{CC} = 3.3$  V



- (1)  $T_{amb} = 125\text{ }^{\circ}\text{C}$ .
- (2)  $T_{amb} = 85\text{ }^{\circ}\text{C}$ .
- (3)  $T_{amb} = 25\text{ }^{\circ}\text{C}$ .
- (4)  $T_{amb} = -40\text{ }^{\circ}\text{C}$ .

Fig 13. ON resistance as a function of input voltage;  $V_{CC} = 5.0\text{ V}$

## 11. Dynamic characteristics

**Table 9. Dynamic characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 16](#).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
$t_{pd}$	propagation delay	nY to nZ or nZ to nY; see <a href="#">Figure 14</a> <sup>[2][3]</sup>						
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	-	0.8	2.0	-	3.0	ns
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	-	0.4	1.2	-	2.0	ns
		$V_{CC} = 2.7\text{ V}$	-	0.4	1.0	-	1.5	ns
		$V_{CC} = 3.0\text{ V to }3.6\text{ V}$	-	0.3	0.8	-	1.5	ns
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	-	0.2	0.6	-	1.0	ns
$t_{en}$	enable time	nE to nY or nZ; see <a href="#">Figure 15</a> <sup>[4]</sup>						
		$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	1.0	4.6	10	1.0	13.0	ns
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.0	2.7	5.6	1.0	7.5	ns
		$V_{CC} = 2.7\text{ V}$	1.0	2.7	5.0	1.0	6.5	ns
		$V_{CC} = 3.0\text{ V to }3.6\text{ V}$	1.0	2.4	4.4	1.0	6.0	ns
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	1.0	1.8	3.9	1.0	5.0	ns

**Table 9. Dynamic characteristics ...continued**At recommended operating conditions; voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 16](#).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
t <sub>dis</sub>	disable time	nE to nY or nZ; see <a href="#">Figure 15</a>						
		V <sub>CC</sub> = 1.65 V to 1.95 V	1.0	3.8	9.0	1.0	11.5	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.0	2.1	5.5	1.0	7.0	ns
		V <sub>CC</sub> = 2.7 V	1.0	3.5	6.5	1.0	8.5	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	1.0	3.0	6.0	1.0	8.0	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V	1.0	2.2	5.0	1.0	6.5	ns
C <sub>PD</sub>	power dissipation capacitance	C <sub>L</sub> = 50 pF; f <sub>i</sub> = 10 MHz; V <sub>I</sub> = GND to V <sub>CC</sub>						
		V <sub>CC</sub> = 2.5 V	-	9.0	-	-	-	pF
		V <sub>CC</sub> = 3.3 V	-	11.0	-	-	-	pF
		V <sub>CC</sub> = 5.0 V	-	15.7	-	-	-	pF

[1] Typical values are measured at T<sub>amb</sub> = 25 °C and nominal V<sub>CC</sub>.[2] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>.

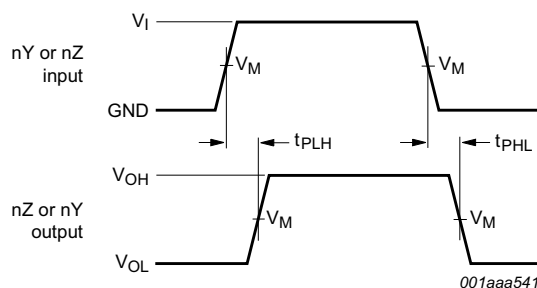
[3] Propagation delay is the calculated RC time constant of the typical ON resistance of the switch and the specified capacitance when driven by an ideal voltage source (zero output impedance).

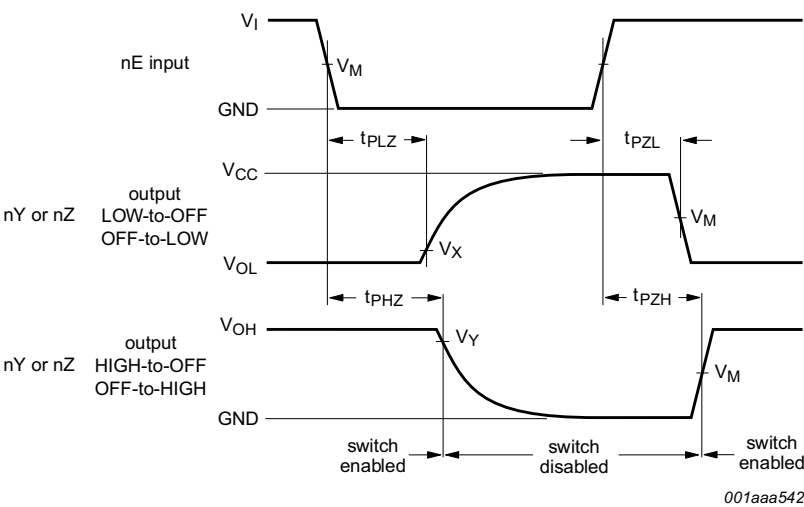
[4] t<sub>en</sub> is the same as t<sub>PZH</sub> and t<sub>PZL</sub>.[5] t<sub>dis</sub> is the same as t<sub>PLZ</sub> and t<sub>PHZ</sub>.[6] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).
$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma\{(C_L + C_{S(ON)}) \times V_{CC}^2 \times f_o\}$$
 where:
f<sub>i</sub> = input frequency in MHz;f<sub>o</sub> = output frequency in MHz;C<sub>L</sub> = output load capacitance in pF;C<sub>S(ON)</sub> = maximum ON-state switch capacitance in pF;V<sub>CC</sub> = supply voltage in V;

N = number of inputs switching;

Σ{(C<sub>L</sub> + C<sub>S(ON)</sub>) × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>} = sum of the outputs.

## 11.1 Waveforms and test circuit

Measurement points are given in [Table 10](#).Logic levels: V<sub>OL</sub> and V<sub>OH</sub> are typical output voltage levels that occur with the output load.**Fig 14. Input (nY or nZ) to output (nZ or nY) propagation delays**

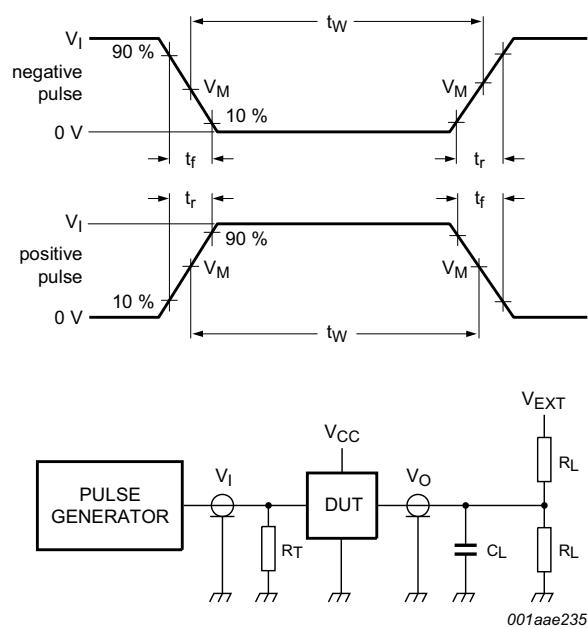


Measurement points are given in [Table 10](#).  
Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

Fig 15. Enable and disable times

Table 10. Measurement points

Supply voltage	Input	Output		
$V_{CC}$	$V_M$	$V_M$	$V_X$	$V_Y$
1.65 V to 1.95 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$V_{OL} + 0.15 \text{ V}$	$V_{OH} - 0.15 \text{ V}$
2.3 V to 2.7 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$V_{OL} + 0.15 \text{ V}$	$V_{OH} - 0.15 \text{ V}$
2.7 V	1.5 V	1.5 V	$V_{OL} + 0.3 \text{ V}$	$V_{OH} - 0.3 \text{ V}$
3.0 V to 3.6 V	1.5 V	1.5 V	$V_{OL} + 0.3 \text{ V}$	$V_{OH} - 0.3 \text{ V}$
4.5 V to 5.5 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$V_{OL} + 0.3 \text{ V}$	$V_{OH} - 0.3 \text{ V}$



Test data is given in [Table 11](#).  
Definitions for test circuit:  
 $R_L$  = Load resistance.  
 $C_L$  = Load capacitance including jig and probe capacitance.  
 $R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.  
 $V_{EXT}$  = Test voltage for switching times.

Fig 16. Test circuit for measuring switching times

Table 11. Test data

Supply voltage	Input		Load		$V_{EXT}$		
$V_{CC}$	$V_I$	$t_r, t_f$	$C_L$	$R_L$	$t_{PLH}, t_{PHL}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$
1.65 V to 1.95 V	$V_{CC}$	$\leq 2.0$ ns	30 pF	1 k $\Omega$	open	GND	$2 \times V_{CC}$
2.3 V to 2.7 V	$V_{CC}$	$\leq 2.0$ ns	30 pF	500 $\Omega$	open	GND	$2 \times V_{CC}$
2.7 V	2.7 V	$\leq 2.5$ ns	50 pF	500 $\Omega$	open	GND	6 V
3.0 V to 3.6 V	2.7 V	$\leq 2.5$ ns	50 pF	500 $\Omega$	open	GND	6 V
4.5 V to 5.5 V	$V_{CC}$	$\leq 2.5$ ns	50 pF	500 $\Omega$	open	GND	$2 \times V_{CC}$

## 11.2 Additional dynamic characteristics

**Table 12. Additional dynamic characteristics**

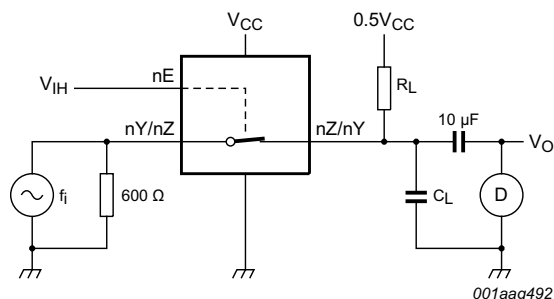
At recommended operating conditions; voltages are referenced to GND (ground = 0 V);  $T_{amb} = 25\text{ }^{\circ}\text{C}$ .

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
THD	total harmonic distortion	$R_L = 10\text{ k}\Omega$ ; $C_L = 50\text{ pF}$ ; $f_i = 1\text{ kHz}$ ; see <a href="#">Figure 17</a>				
		$V_{CC} = 1.65\text{ V}$	-	0.032	-	%
		$V_{CC} = 2.3\text{ V}$	-	0.008	-	%
		$V_{CC} = 3.0\text{ V}$	-	0.006	-	%
		$V_{CC} = 4.5\text{ V}$	-	0.005	-	%
		$R_L = 10\text{ k}\Omega$ ; $C_L = 50\text{ pF}$ ; $f_i = 10\text{ kHz}$ ; see <a href="#">Figure 17</a>				
		$V_{CC} = 1.65\text{ V}$	-	0.068	-	%
		$V_{CC} = 2.3\text{ V}$	-	0.009	-	%
		$V_{CC} = 3.0\text{ V}$	-	0.008	-	%
		$V_{CC} = 4.5\text{ V}$	-	0.006	-	%
$f_{(-3\text{dB})}$	-3 dB frequency response	$R_L = 600\text{ }\Omega$ ; $C_L = 50\text{ pF}$ ; see <a href="#">Figure 18</a>				
		$V_{CC} = 1.65\text{ V}$	-	135	-	MHz
		$V_{CC} = 2.3\text{ V}$	-	145	-	MHz
		$V_{CC} = 3.0\text{ V}$	-	150	-	MHz
		$V_{CC} = 4.5\text{ V}$	-	155	-	MHz
		$R_L = 50\text{ }\Omega$ ; $C_L = 10\text{ pF}$ ; see <a href="#">Figure 18</a>				
		$V_{CC} = 1.65\text{ V}$	-	200	-	MHz
		$V_{CC} = 2.3\text{ V}$	-	350	-	MHz
		$V_{CC} = 3.0\text{ V}$	-	410	-	MHz
		$V_{CC} = 4.5\text{ V}$	-	440	-	MHz
		$R_L = 50\text{ }\Omega$ ; $C_L = 5\text{ pF}$ ; see <a href="#">Figure 18</a>				
		$V_{CC} = 1.65\text{ V}$	-	> 500	-	MHz
		$V_{CC} = 2.3\text{ V}$	-	> 500	-	MHz
		$V_{CC} = 3.0\text{ V}$	-	> 500	-	MHz
		$V_{CC} = 4.5\text{ V}$	-	> 500	-	MHz
$\alpha_{iso}$	isolation (OFF-state)	$R_L = 600\text{ }\Omega$ ; $C_L = 50\text{ pF}$ ; $f_i = 1\text{ MHz}$ ; see <a href="#">Figure 19</a>				
		$V_{CC} = 1.65\text{ V}$	-	-46	-	dB
		$V_{CC} = 2.3\text{ V}$	-	-46	-	dB
		$V_{CC} = 3.0\text{ V}$	-	-46	-	dB
		$V_{CC} = 4.5\text{ V}$	-	-46	-	dB
		$R_L = 50\text{ }\Omega$ ; $C_L = 5\text{ pF}$ ; $f_i = 1\text{ MHz}$ ; see <a href="#">Figure 19</a>				
		$V_{CC} = 1.65\text{ V}$	-	-37	-	dB
		$V_{CC} = 2.3\text{ V}$	-	-37	-	dB
		$V_{CC} = 3.0\text{ V}$	-	-37	-	dB
		$V_{CC} = 4.5\text{ V}$	-	-37	-	dB

**Table 12. Additional dynamic characteristics ...continued**At recommended operating conditions; voltages are referenced to GND (ground = 0 V);  $T_{amb} = 25\text{ }^{\circ}\text{C}$ .

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{ct}$	crosstalk voltage	between digital inputs and switch; $R_L = 600\text{ }\Omega$ ; $C_L = 50\text{ pF}$ ; $f_i = 1\text{ MHz}$ ; $t_r = t_f = 2\text{ ns}$ ; see <a href="#">Figure 20</a>				
		$V_{CC} = 1.65\text{ V}$	-	-	-	mV
		$V_{CC} = 2.3\text{ V}$	-	91	-	mV
		$V_{CC} = 3.0\text{ V}$	-	119	-	mV
		$V_{CC} = 4.5\text{ V}$	-	205	-	mV
Xtalk	crosstalk	between switches; $R_L = 600\text{ }\Omega$ ; $C_L = 50\text{ pF}$ ; $f_i = 1\text{ MHz}$ ; see <a href="#">Figure 21</a>				
		$V_{CC} = 1.65\text{ V}$	-	-	-	dB
		$V_{CC} = 2.3\text{ V}$	-	-56	-	dB
		$V_{CC} = 3\text{ V}$	-	-56	-	dB
		$V_{CC} = 4.5\text{ V}$	-	-56	-	dB
		between switches; $R_L = 50\text{ }\Omega$ ; $C_L = 5\text{ pF}$ ; $f_i = 1\text{ MHz}$ ; see <a href="#">Figure 21</a>				
		$V_{CC} = 1.65\text{ V}$	-	-	-	dB
		$V_{CC} = 2.3\text{ V}$	-	-29	-	dB
		$V_{CC} = 3\text{ V}$	-	-28	-	dB
		$V_{CC} = 4.5\text{ V}$	-	-28	-	dB
$Q_{inj}$	charge injection	$C_L = 0.1\text{ nF}$ ; $V_{gen} = 0\text{ V}$ ; $R_{gen} = 0\text{ }\Omega$ ; $f_i = 1\text{ MHz}$ ; $R_L = 1\text{ M}\Omega$ ; see <a href="#">Figure 22</a>				
		$V_{CC} = 1.8\text{ V}$	-	3.3	-	pC
		$V_{CC} = 2.5\text{ V}$	-	4.1	-	pC
		$V_{CC} = 3.3\text{ V}$	-	5.0	-	pC
		$V_{CC} = 4.5\text{ V}$	-	6.4	-	pC
		$V_{CC} = 5.5\text{ V}$	-	7.5	-	pC

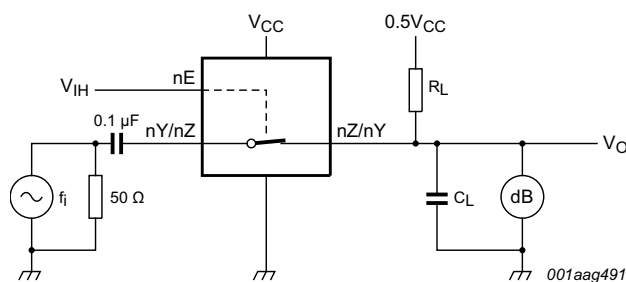
### 11.3 Test circuits



**Test conditions:**

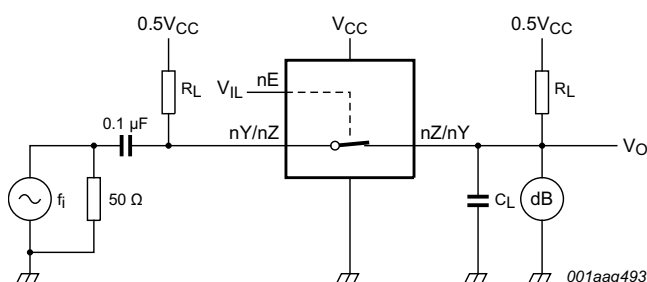
 $V_{CC} = 1.65 \text{ V}; V_i = 1.4 \text{ V (p-p)}.$  $V_{CC} = 2.3 \text{ V}; V_i = 2 \text{ V (p-p)}.$ 
$$V_{CC} = 3 \text{ V}; V_i = 2.5 \text{ V (p-p)}.$$
 $V_{CC} = 4.5 \text{ V}; V_i = 4 \text{ V (p-p)}.$ 

**Fig 17. Test circuit for measuring total harmonic distortion**



To obtain 0 dBm level at output, adjust  $f_i$  voltage. Increase  $f_i$  frequency until dB meter reads  $-3$  dB.

**Fig 18. Test circuit for measuring the frequency response when switch is in ON-state**



To obtain 0 dBm level at input, adjust  $f_i$  voltage.

**Fig 19. Test circuit for measuring isolation (OFF-state)**



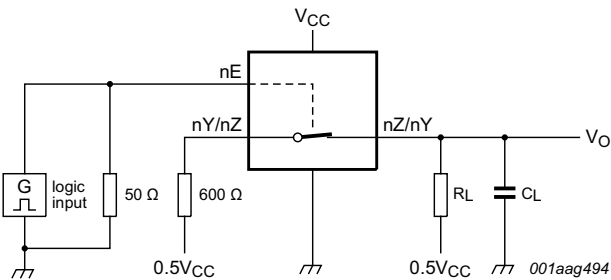
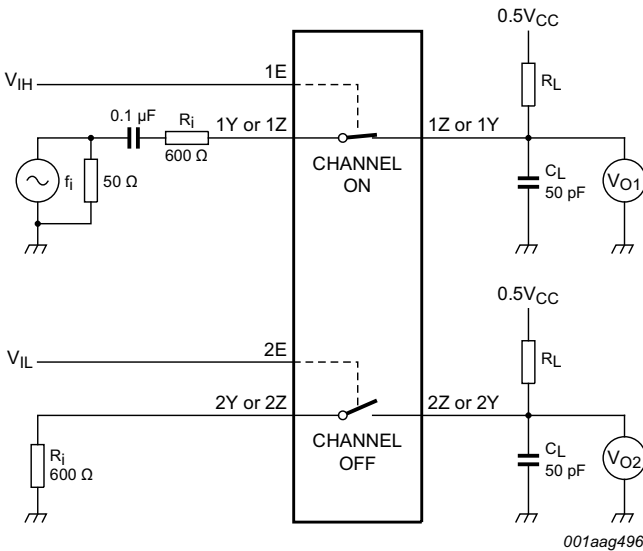
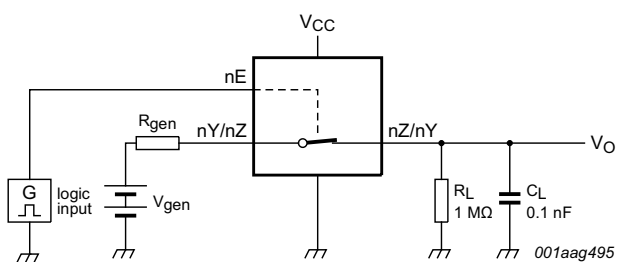


Fig 20. Test circuit for measuring crosstalk voltage (between digital inputs and switch)

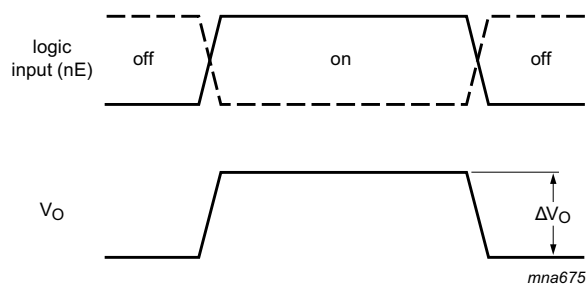


$20 \log_{10} (V_{O2} / V_{O1})$  or  $20 \log_{10} (V_{O1} / V_{O2})$ .

Fig 21. Test circuit for measuring crosstalk between switches



a. Test circuit



b. Input and output pulse definitions

$$Q_{inj} = \Delta V_O \times C_L$$

 $\Delta V_O$  = output voltage variation.

 $R_{gen}$  = generator resistance.

 $V_{gen}$  = generator voltage.

**Fig 22. Test circuit for measuring charge injection**

12. Package outline

TSSOP8: plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm SOT505-2

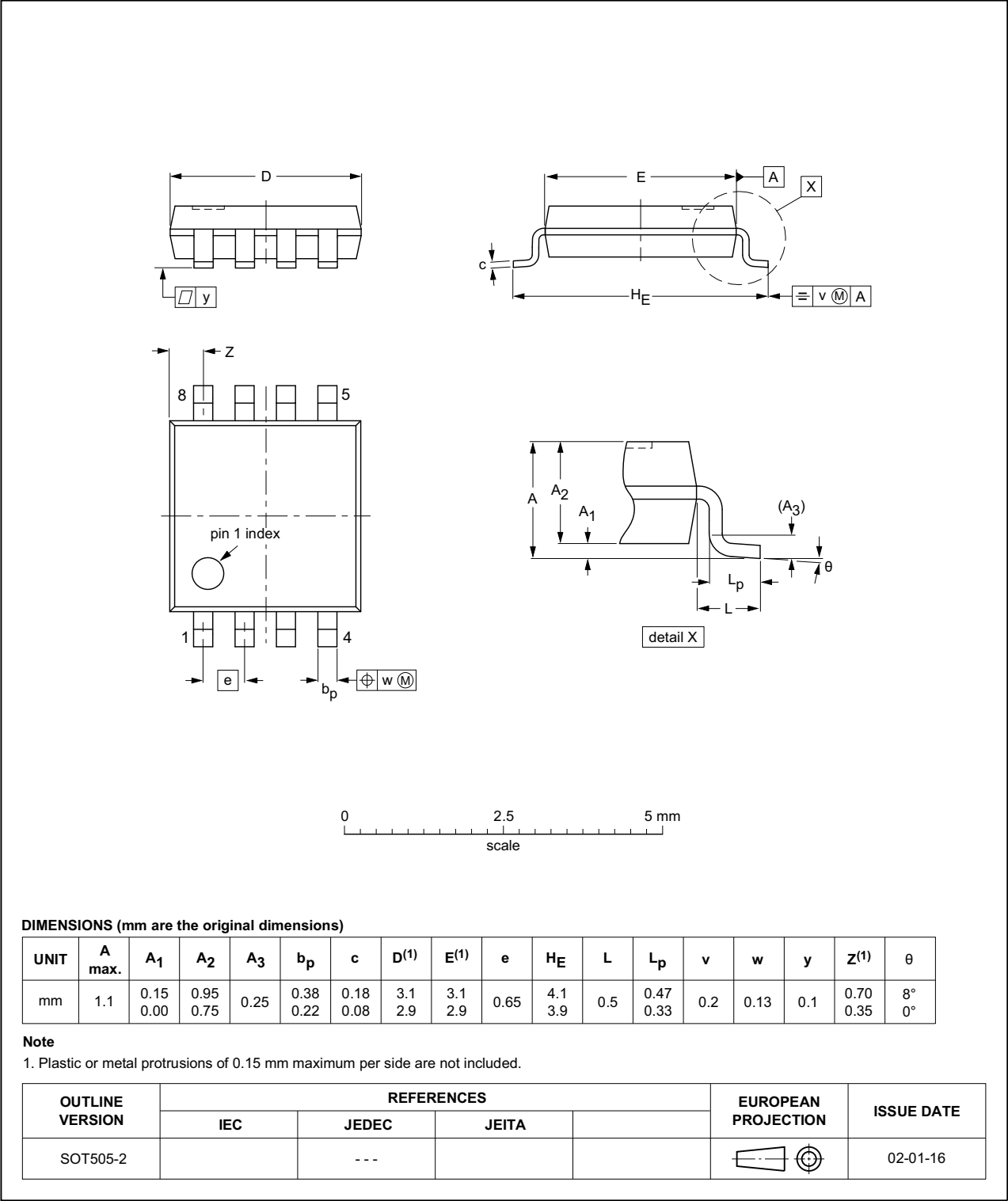


Fig 23. Package outline SOT505-2 (TSSOP8)

VSSOP8: plastic very thin shrink small outline package; 8 leads; body width 2.3 mm

SOT765-1

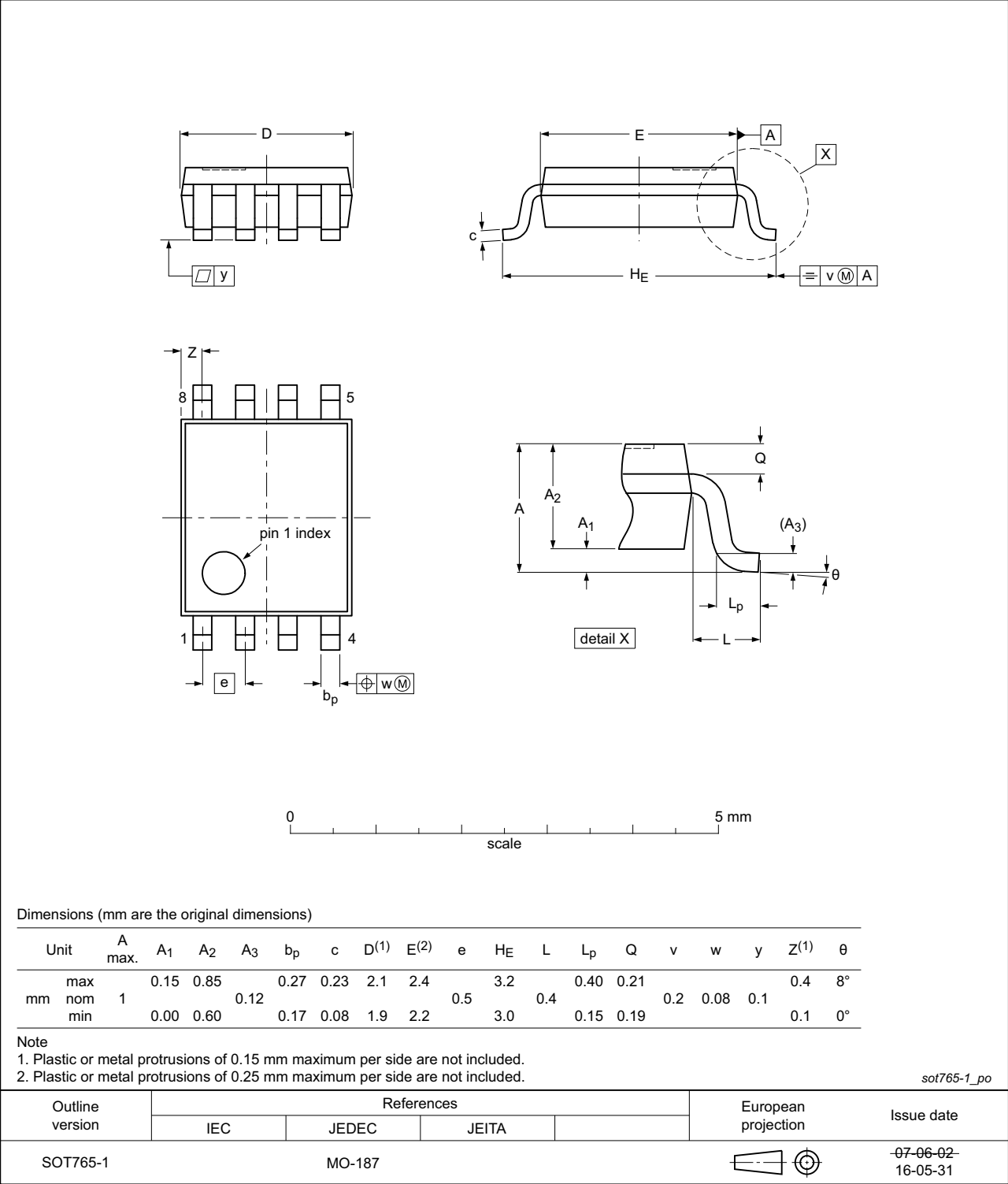


Fig 24. Package outline SOT765-1 (VSSOP8)

## 13. Abbreviations

Table 13. Abbreviations

Acronym	Description
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MIL	Military
MM	Machine Model
TTL	Transistor-Transistor Logic

## 14. Revision history

Table 14. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC2G66_Q100 v.2	20161214	Product data sheet	-	74LVC2G66_Q100 v.1
Modifications:	• <a href="#">Table 7</a> : The maximum limits for leakage current and supply current have changed.			
74LVC2G66_Q100 v.1	20130416	Product data sheet	-	-

## 15. Legal information

### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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